

| Feature | Standard | Advanced |
|---|--|--|
| Materials | RIGID: CEM1, CEM3, FR4, Teflon FLEX: FR4, Kapton, Polyimide IMS: AL BASED | RIGID: on demand: low/super low/ultra low loss material IMS: CU BASED |
| Minimum dielectric thickness | 0.05mm for PCB 0.025mm for FPC | 0.025mm for PCB 0.012mm for FPC |
| Layer count | 1 – 8 L | 24 L |
| HDI / Buried – blind via | Y | Y |
| Maximum board size (mm) | 546 X 622 | 600 X 1100 |
| Minimum board thickness (mm) 2L | 0.4mm for PCB 0.05mm for 1L FPC 0.12mm for 2L FPC | 0.15mm for PCB 0.05mm for 1L FPC 0.12mm for 2L FPC |
| Maximum board thickness (mm) | 3.2mm | on demand |
| Minimum track / gap Inner layer(mil) – based on copper weight | 0.075mm | 0.05mm |
| Minimum track / gap Outer layer (mil) – based on copper weight | 0.075mm | 0.05mm |
| Surface finish | ENIG / OSP / I Ag / HASL (lead) / HASL (Leadfree) / Immersion Sn / | Hard Gold / ENEPIG / Hard Gold + OSP / Combined Finishes |
| Layer to layer registration | 0.05mm | 25µm |
| Minimum hole (mech) (mm/mil) | 0.15mm | 0.1mm |
| Minimum hole (laser) (mm/mil) | 0.075 | 0,05 |
| Aspect ratio PTH | 08:01 | 01:01 |
| Aspect ration BVH | 0.8:1 | 01:01 |
| Finish hole tolerance (PTH) | ± 0.076mm | ± 0.05mm |
| Finish hole tolerance (NPTH) | ± 0.05mm | ± 0.0375mm |
| Maximum Cu weight OL | 4oz | 10oz |
| Maximum Cu weight IL | 4oz | 10oz |
| Controlled impedance (+/- X%) | ± 10% | ± 5% |

